

FluxPlus Paste Flux

Versatile paste flux improves the soldering process



FluxPlus is perfect for BGA rework, mobile device repair, reflowing solder paste, and more.



PICO Pulse® jetting FluxPlus onto a PCB.



Performus™ X100 dispensing FluxPlus onto a PCB.

Flux is the linchpin that holds the soldering process together. High quality solder joints are made possible through the cleaning action of our FluxPlus™ paste flux. Regardless of your industry, your goal is to apply the right amount of flux, no more and no less, to the right location every time. You want the flux to stay where it is placed and secure your parts until heat is applied.

Features and Benefits

- Controlled flux spread as a result of precise dispensing
- Holds small parts in place before soldering
- Delivers more flux compared to flux-core wire solder
- Formulas for wetting to difficult-to-solder surfaces (stainless steel, etc.)
- Convenient sizes: 10cc, 30cc, 55cc, and 70cc syringes; 6 oz cartridges; and 2 oz and 6 oz jars
- Compatible with range of dispensing solutions, including jetting systems

Applications

- Manufacture and repair of BGAs (screen printing materials with contrasting color)
- SMT rework and repair
- Fluxing of pre-bumped solder pads
- Prototype development and production



more info



FluxPlus Formulations

Flux Type	Dispensing flux							Printing flux		
	RMA	RA	NC	WS	WS	WS	WS	RMA	NC	WS
Flux Class J-STD-004B	ROL0	ROL1	ROL1	ORH1	ORH1	ORL0	ORH1	ROL0	ROL1	ORL0
Formula	07D00	41D00	21D00	71D00	72D00	63D00	67D00	08P00	27P00	45P00
Aluminum	Non-solderable									
Beryllium Copper	●	●	●	●	✗	●	●	●	●	●
Brass	■	●	■	●	●	■	●	■	■	▲
Bronze	■	●	■	●	●	■	●	■	■	▲
Cadmium	●	●	▲	●	✗	●	●	●	▲	▲
Chromium	Non-solderable									
Copper	●	●	●	●	✗	●	●	●	●	●
Galvanized Steel	✗	▲	✗	●	●	✗	✗	✗	✗	✗
Gold	●	●	●	●	✗	●	●	●	●	●
Kovar	▲	●	✗	●	●	✗	▲	▲	✗	✗
Magnesium	Non-solderable									
Mild Steel	✗	▲	✗	●	●	✗	▲	✗	✗	✗
Monel	✗	▲	✗	●	●	✗	▲	✗	✗	✗
Nichrome	✗	✗	✗	✗	●	✗	✗	✗	✗	✗
Nickel	●	●	▲	●	●	▲	●	▲	▲	▲
Nickel Iron / Alloy42	▲	●	✗	●	●	✗	▲	▲	✗	✗
Nickel Silver	●	●	▲	●	✗	▲	●	▲	▲	▲
Palladium	●	●	●	●	✗	●	●	●	●	●
Platinum	●	●	●	●	✗	●	●	●	●	●
Silver	●	●	●	●	✗	●	●	●	●	●
Solder Plated	●	●	●	●	✗	●	●	●	●	●
Stainless Steel	✗	✗	✗	✗	■	✗	✗	✗	✗	✗
Tin	●	●	●	●	✗	●	●	●	●	●
Titanium	Non-solderable									
Zinc	✗	▲	✗	●	●	✗	▲	✗	✗	✗

Legend	Flux Types		Recommended Use	
	RMA	Rosin mildly activated	●	Recommended
RA	Rosin activated	▲	Wets clean surfaces	
NC	No clean	■	Alloy specific (contact EFD)	
WS	Water soluble	✗	Not recommended	



FluxPlus Formulations

Rosin Mildly Activated (RMA)

Mildly activated rosin flux consists of rosin, solvent, and a small amount of activator. RMA flux residue is clear, soft, non-corrosive, and inert. Cleaning is optional. Residue may be either left on your assembly after soldering or cleaned off with an appropriate solvent.

Code	Type	Flux Class	Alloy Compatibility	Features
0700	Dispense	ROL0	All standard alloys	All purpose RMA flux. Restrictive spread
08P00	Print	ROL0	All standard alloys	Low slump during heating for BGAs

Rosin Activated (RA)

Rosin activated flux consists of rosin, solvent, and aggressive activators. RA flux residue is corrosive and should be removed after reflow to prevent damage to your assembly. Residue may be removed with an appropriate solvent.

Code	Type	Flux Class	Alloy Compatibility	Features
41D00	Dispense	ROL1	All standard alloys	All purpose RA flux

No Clean (NC)

No clean flux consists of rosin, solvent, and a small amount of activator. NC flux residue is hard, non-corrosive, inert, and designed to be left on your assembly. Residue may be removed with an appropriate solvent if so desired.

Code	Type	Flux Class	Alloy Compatibility	Features
21D00	Dispense	ROL1	All standard alloys	All purpose no-clean flux
27P00	Print	ROL1	All standard alloys	High temperature flux for BGAs

Water Soluble (WS)

Water soluble flux consists of organic acids, thixotrope, and solvent. WS flux residue is corrosive and should be removed within 96 hours of reflow to avoid damage to your assembly. Residue may be removed with water at 60° C (140° F) and 40 psi of pressure.

Code	Type	Flux Class	Alloy Compatibility	Features
63D00	Dispense	ROL0	Alloys soldered below 250° C	All purpose WS flux
67D00	Dispense	ORH1	Alloys soldered above 200° C	High temperature flux
65P00	Print	ROL0	All standard alloys	Low slump during heating for BGAs
72D00	Dispense	ORH1	Alloys soldered above 170° C	For difficult to solder materials
71D00	Dispense	ORH1	Alloys soldered above 170° C	For stainless steel and other difficult materials

Quality

FluxPlus paste fluxes meet or exceed IPC Joint Industry Standard J-STD-004B for flux.

Storage and Handling

Store between 40° and 77° F (4° and 25° C). When not in use, containers should be kept closed.

Guarantee

Nordson EFD FluxPlus paste fluxes have a guaranteed shelf life of six (6) months from date of shipment when stored as recommended.

Safety

Read MSDS prior to use. Care should be taken to prevent accidental ingestion or contact with eyes. Soldering with this product can produce hazardous fumes. Use adequate ventilation and avoid breathing soldering fumes. Wash hands thoroughly after use.

Request samples

If you'd like to test EFD FluxPlus paste flux, please request samples. Simply go to www.nordsonefd.com/FluxPasteRequest.

Request more information

Call or email us for a consultation with one of our Application Specialists to review your application requirements.

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Connect with us



For Nordson EFD sales and service in over 40 countries, contact Nordson EFD or go to www.nordsonefd.com.

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